

REMARKS

Claims 1-24 were pending prior to entry of the amendments herein. Claims 11-15 and 22-24 are canceled herein. Claims 1 and 16 are amended herein. New Claims 25 and 26 are added.

Specification

The specification has been amended to include the patent number of the parent application, in accordance with the Examiner's suggestion.

Rejections Under 35 U.S.C. §102

Claims 1-5, 7-9, 16-19, and 21 are rejected under 35 U.S.C. §102(e)/(a) as being anticipated by Hongo et al., U.S. Patent No. 6,615,854. Claim 1 is amended to recite forming conductive material onto the seed layer coating the front edge surface and the front surface of the wafer after removing the seed layer from the back edge surface and the bevel surface. Claim 16 is similarly amended to recite forming the layer by depositing the conductive material onto the seed layer coating the front edge surface and the front surface after removing the seed layer from the back edge surface and the bevel surface. These amendments are fully supported by the specification, as originally filed, at, for example, paragraphs [0026]-[0028] and Figs. 3 and 4.

Hongo et al. do not disclose or suggest forming conductive material onto the seed layer coating the front edge surface and the front surface of the wafer after removing the seed layer from the back edge surface and the bevel surface, as recited in amended independent Claim 1. Similarly, Hongo et al. do not disclose or suggest forming the layer by depositing the conductive material onto the seed layer coating the front edge surface and the front surface after removing the seed layer from the back edge surface and the bevel surface, as recited in amended independent Claim 16. The edge removal of Hongo et al. involves etching the "seed layer 83 and the plating layer 85 together at thin portion U." Hongo et al., at col. 4, lines 53-55 (emphasis added) and Fig. 7. Thus, in Hongo et al., edge removal occurs after plating such that the plating layer 85 is not formed after the seed layer 83 is removed from the back surface and bevel surface, as the plating layer 85 and seed layer 83 are removed together.

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Claims 1 and 16, as amended, are therefore patentable as they are not anticipated by Hongo et al. Claims 2-5, 7-9, 17-19, and 21, which depend from and include all of the limitations of amended Claim 1 or 16, are therefore also patentable over Hongo et al. Furthermore, each of the dependent claims recites further distinguishing features of particular utility.

Rejections Under 35 U.S.C. §103

Claims 6, 10, and 20 are rejected under 35 U.S.C. §103(a) as being unpatentable over Hongo et al. taken with Volodarsky et al., U.S. Patent No. 6,352,623. As discussed above, Claims 1 and 16 are not anticipated by Hongo et al. Volodarsky et al. do not make up for the deficiencies of Hongo et al. discussed above.

Without acquiescing in the Examiner's reasons for rejections, Applicants submit that Claims 6, 10, and 20 are allowable at least because they include all of the limitations of amended Claim 1 or 16, which are patentable, as discussed above. Furthermore, the dependent claims recite further distinguishing features of advantage and utility.

New Claims

New Claims 25 and 26 are added, and are fully supported by the specification and claims, as originally filed. No new matter is added by new Claims 25 and 26.

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Conclusion

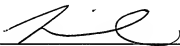
Applicants respectfully submit that all of the pending claims are patentably distinguishable over the art of record. The cited references, either alone or in combination do not teach or suggest Applicants' claimed invention.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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AMEND

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